IN THE CLAIMS:

Amend claims 1-13 as shown on the following pages.

1. (Currently Amended). A method of ~~system for~~ maintaining an IC-module near a set-point temperature while electrical power dissipation in said IC-module is varied; said method including the steps ~~system being comprised~~ of:

pressing an open end of a container against said IC-module such that a leak free seal is formed between said container and said IC-module;

spraying a liquid coolant onto said IC-module, during said pressing step, from at least one nozzle in said container; and,

keeping said IC-module at a set-point which is colder than the boiling point of said liquid coolant at atmospheric pressure, by producing a sub-atmospheric pressure in said container throughout said spraying step.

~~a container having an open end with a seal for pressing against said IC-module;~~

~~at least one nozzle, in said container, for spraying a liquid coolant on said IC-module when said seal is pressed against said IC-module; and~~

~~a pressure reducing means, coupled to said container, for producing a sub-atmospheric pressure between said container and said IC-module when said seal is pressed against said IC-module.~~

2. (Currently Amended). A method ~~system~~ according to claim 1 wherein the temperature of said IC-module is kept, by ~~said pressure reducing means produces~~ said sub-atmospheric pressure, ~~such that the boiling point of said liquid coolant is lowered by~~ at least 10°C below the ~~from its~~ boiling point of said liquid coolant at atmospheric pressure.

3. (Currently Amended). A method ~~system~~ according to claim 2 wherein ~~said pressure reducing means reduces~~ said sub-atmospheric pressure in said container is reduced to a point where essentially all of said liquid coolant from each nozzle rapidly vaporizes when it hits said IC-module.

4. (Currently Amended). A method ~~system~~ according to claim 2 wherein said liquid coolant circulates through ~~which further includes~~ a circulation subsystem which is[[,]] coupled to each nozzle, ~~that holds said liquid coolant,~~ and wherein said liquid coolant consists essentially of water.

5. (Currently Amended). A method ~~system~~ according to claim 2 wherein ~~which includes~~ multiple nozzles are ~~at~~ spaced-apart ~~locations~~ in said container, and each nozzle receives ~~includes a means for receiving~~ one control signal and ejects ~~a means for ejecting~~ just a single droplet of said liquid coolant when it receives said one control signal.

6. (Currently Amended). A method ~~system~~ according to claim 5 which further includes the steps of: ~~a closed-loop control means for:~~ a) receiving a sensor signal representing a sensed temperature of said IC-module, and b) sending said control signal to all of said nozzles simultaneously with a frequency that increases as the differences between said sensed temperature and said set-point increases.

7. (Currently Amended). A method ~~system~~ according to claim 5 which further includes the steps of: ~~a closed-loop control means for:~~ a) receiving a sensor signal representing a sensed temperature of said IC-module, b) sending said control signal to a subset of said nozzles simultaneously, and c) increasing the number of nozzles in said subset as the difference between said sensed temperature and said set-point increase.

8. (Currently Amended). A method ~~system~~ according to claim 5 wherein ~~said means for ejecting in~~ each nozzle ejects each ~~said single~~ droplet by squeezing said coolant with a piezoelectric device.

9. (Currently Amended). A method ~~system~~ according to claim 5 wherein ~~said means for ejecting in~~ each nozzle ejects each ~~said single~~ droplet by heating said coolant with an electric heater.

10. (Currently Amended). A method ~~system~~ according to claim 2 wherein each nozzle receives ~~includes a means for receiving~~ one control signal and sprays ~~a means for spraying~~ multiple droplets of said liquid coolant when it receives said one control signal.

11. (Currently Amended). A method ~~system~~ according to claim 10 which further includes the steps of: ~~a closed-loop control means for:~~ a) receiving a sensor signal representing a sensed temperature of said IC-module, and b) sending said control signal with an ON-OFF ratio that increases as the difference between said sensed temperature and said set-point increases.

12. (Currently Amended). A method ~~system~~ according to claim 2 wherein said seal is formed by encircling ~~shaped to encircle~~ a surface on said IC-module which encloses an IC-chip.

13. (Currently Amended). A method ~~system~~ according to claim 2 wherein said seal is formed by encircling ~~shaped to encircle~~ an exposed surface on an IC-chip in said IC-module.